IN THE CLAIMS:

Claims 2, 7-12, 14, and 19-23 were previously cancelled. Claims 3, 4, 6, 13, 15, 16 and 18 have been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1. (Previously presented) A resist removal method for use in an automolding system comprising:
providing an automolding system having a laser;
providing a substrate having a surface;
forming resist on at least a portion of the surface; and

- 2. (Cancelled)
- 3. (Currently amended) The method according to claim 1 wherein-said_the_laser comprises one of an Nd:YAG laser and an excimer laser.

removing at least a portion of the resist from the substrate using the laser.

- 4. (Currently amended) The method according to claim 1 wherein-said the substrate comprises a ball-grid-array substrate.
- 5. (Original) The method according to claim 1 further comprising a vision system for detecting resist.

6. (Currently amended) The method according to claim 5 wherein said the vision system comprises:

providing a laser scanning system; and detecting changes in a pattern of the substrate.

7.-12. (Cancelled)

13. (Previously presented) A method of fabricating a semiconductor device in an automolding system comprising:

providing an automolding system having a laser for etching resist from the <u>a</u> surface of a substrate;

providing a substrate having a surface;

forming resist on at least a portion of the surface;

laser etching the resist from at least a portion of the surface of the substrate; and encapsulating the substrate.

- 14. (Cancelled)
- 15. (Currently amended) The method according to claim 13 wherein-said-the laser comprises one of an Nd:YAG laser and an excimer laser.
- 16. (Currently amended) The method according to claim 13 wherein said the substrate comprises a ball-grid-array substrate.
- 17. (Original) The method according to claim 13 further comprising a vision system for detecting resist.

18. (Currently amended) The method according to claim 17 wherein-said_the_vision system comprises:

providing a laser scanning system; and detecting changes in a pattern of the substrate.

19.-23. (Cancelled)